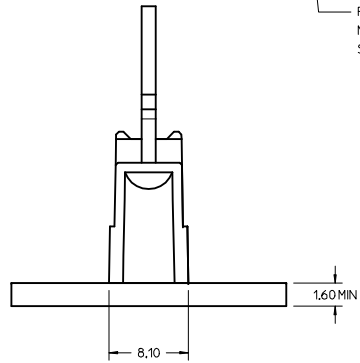
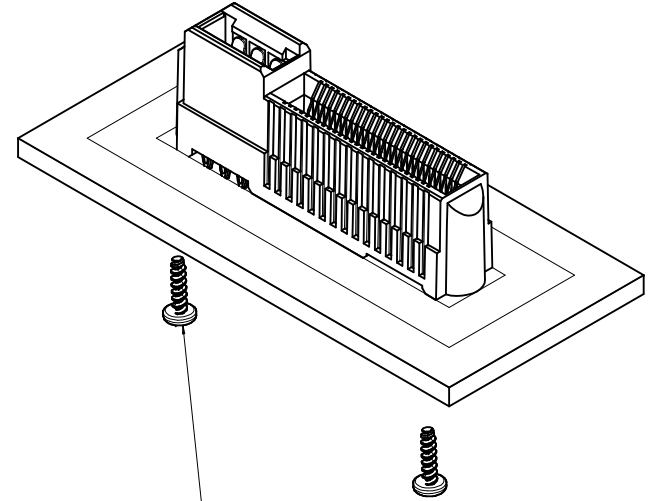
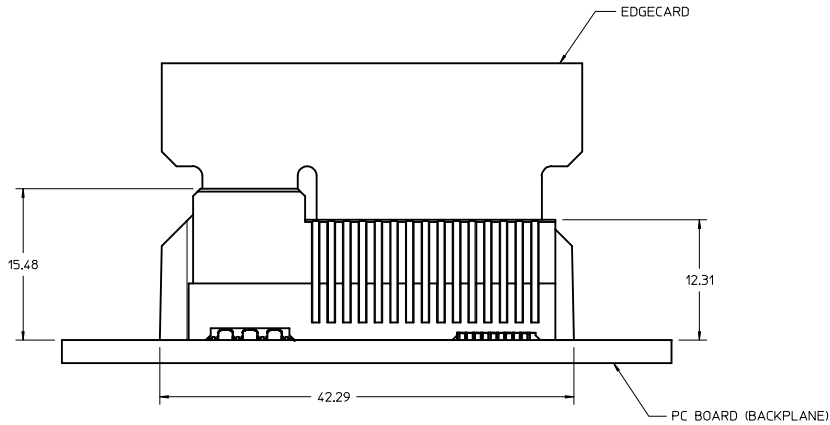
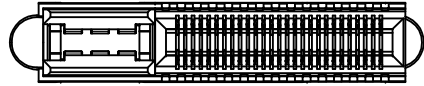


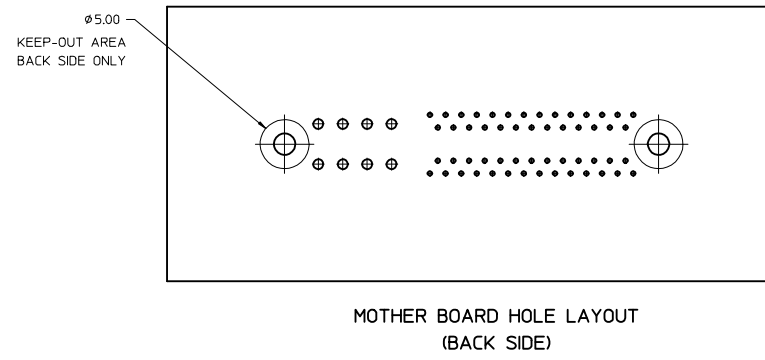
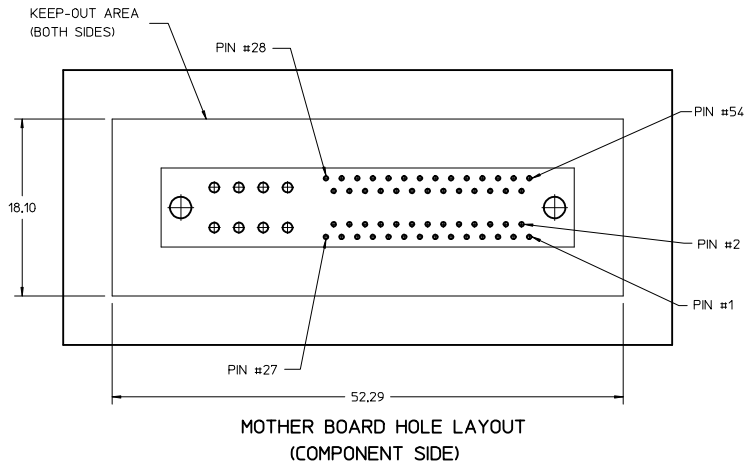
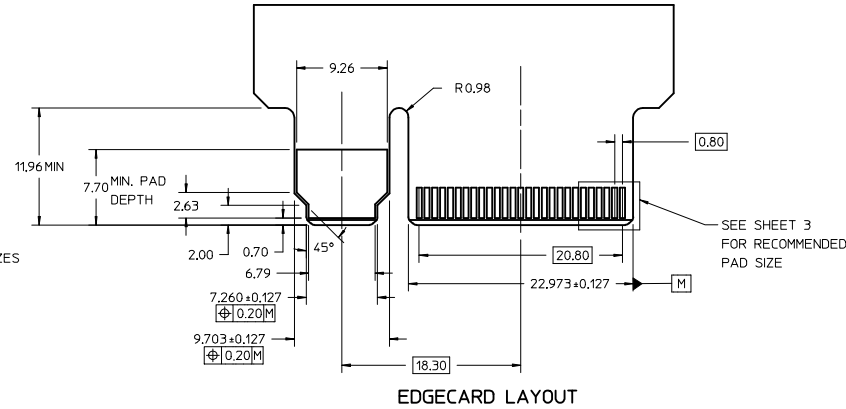
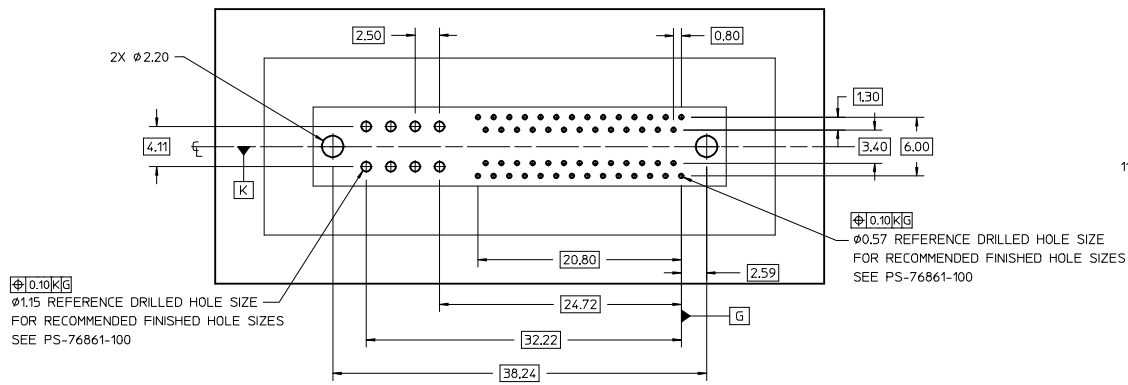
P.C. BOARD MOUNTING



NOTES:

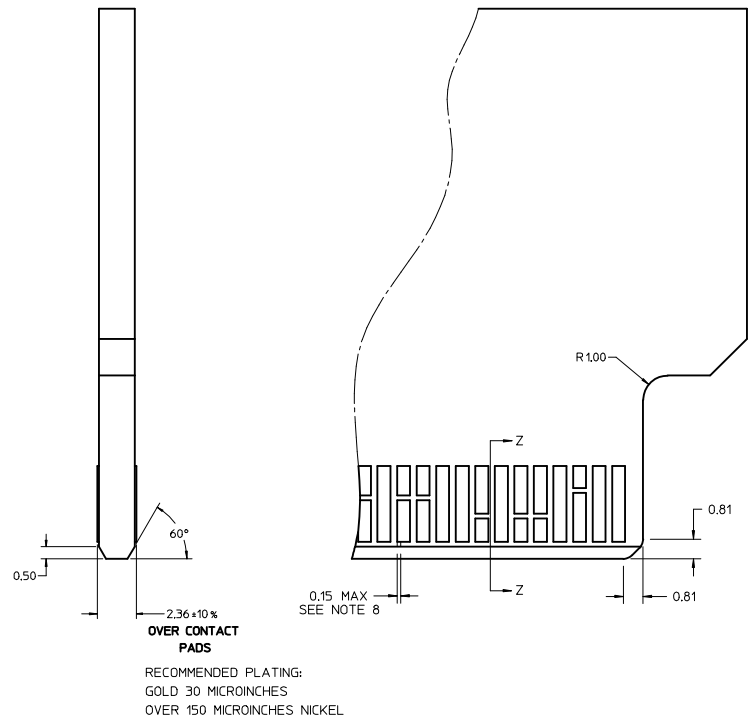
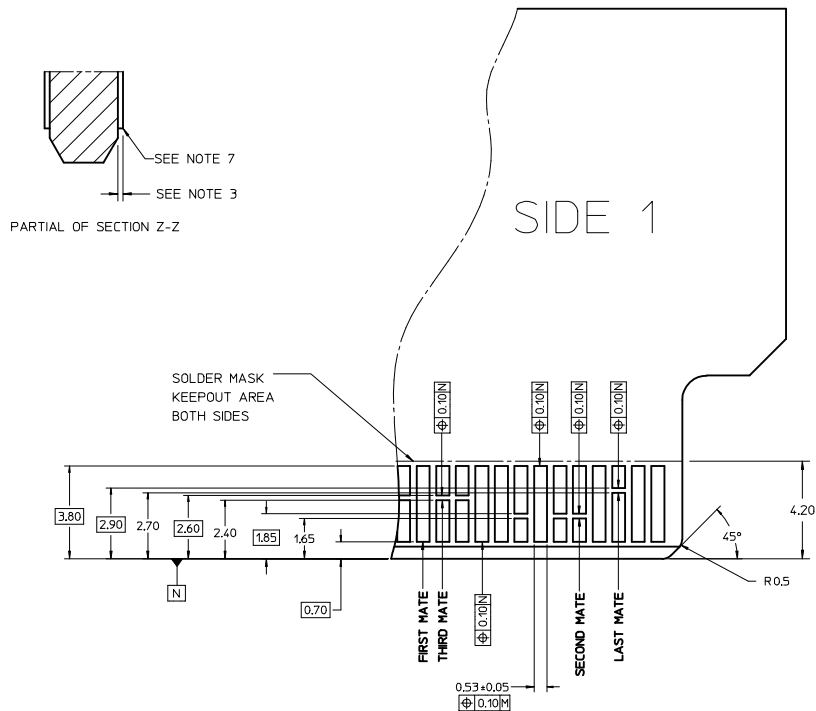
1. MATERIAL:
HOUSING - GLASS FILLED THERMOPLASTIC, 94-V0, BLACK
TERMINALS - COPPER ALLOY
2. FINISH:
CONTACT AREA: HARD GOLD -0.76 MICROMETERS MINIMUM OVER 3.80 MICRO METER NICKEL
COMPLIANT AREA: TIN - 0.76/1.52 MICROMETERS OVER NICKEL
3. REFER TO PS-76861-100 PRODUCT SPECIFICATION FOR ALL ELECTRICAL, MECHANICAL AND ENVIRONMENTAL SPECIFICATIONS.
4. REFER TO PK-170545-5000 FOR ALL PACKAGING SPECIFICATIONS.
5. REFER TO AS-76693-100 FOR APPLICATION SPECIFICATIONS.
6. PROCESSING: PRESSFIT TO PC BOARD.
7. MATING PC BOARD THICKNESS = 2.36±10% OVER CONTACT PADS.
8. THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPEC PS-45499-002

TOLERANCE TYPO CORRECTION IEC NO: UICP2017-1945 DRAWN BY: MPOFF 2017/03/09 CHECKED BY: DMORGAN 2017/03/09 APPR: KLANG 2017/03/15 REV DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0		GENERAL TOLERANCES (UNLESS SPECIFIED) <table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> </thead> <tbody> <tr> <td>4 PLACES</td> <td>±---</td> <td>±---</td> </tr> <tr> <td>3 PLACES</td> <td>±---</td> <td>±---</td> </tr> <tr> <td>2 PLACES</td> <td>±0.13</td> <td>±---</td> </tr> <tr> <td>1 PLACE</td> <td>±0.25</td> <td>±---</td> </tr> <tr> <td>0 PLACE</td> <td>±---</td> <td>±---</td> </tr> </tbody> </table>			mm	INCH	4 PLACES	±---	±---	3 PLACES	±---	±---	2 PLACES	±0.13	±---	1 PLACE	±0.25	±---	0 PLACE	±---	±---	DIMENSION STYLE MM ONLY	SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		mm	INCH																							
	4 PLACES	±---	±---																							
	3 PLACES	±---	±---																							
2 PLACES	±0.13	±---																								
1 PLACE	±0.25	±---																								
0 PLACE	±---	±---																								
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			MATERIAL NO. 170545-1054	DATE DRAWN BY: MPOFF 2014/05/23 CHECKED BY: DMORGAN 2014/05/23 APPROVED BY: SMILLER 2014/07/23		TITLE EDGELINE ESP30 12.5GB 0.093"PCB/0.8MM PITCH 54 CKTS																				
ANGULAR ± 2 °			DOCUMENT NO. SD-170545-1054		SHEET NO. 1 OF 3																					
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION																										



SEE SHEET 1 IEC NO: UCP2017-1945 DRAWN BY: MPOFF 2017/03/09 CHECKED BY: CHYKDMORGAN 2017/03/09 APPROVED BY: APPR:KLANG 2017/03/15	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		4 PLACES ± 0.13 3 PLACES ± 0.25 2 PLACES ± 0.50 1 PLACE ± 1.00 0 PLACE ± 1.50	mm INCH	DRAWN BY MPOFF	DATE 2014/05/23	TITLE EDGELINE ESP30 12.5GB 0.093"PCB/0.8MM PITCH 54 CKTS	MATERIAL NO. SEE SHEET 1	DOCUMENT NO. SD-170545-1054
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS								
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								

MODULE EDGE CARD CONTACT DETAIL



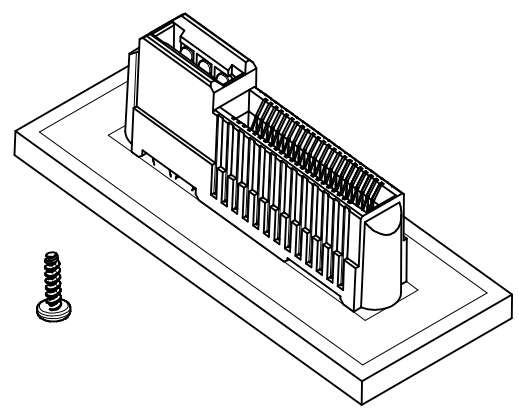
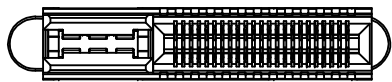
MATING PCB NOTES:

- CONNECTOR LAND CONDITIONS SHALL MEET THE MOST CURRENT REVISION OF PCB SPECIFICATION IPC-6012C-2010 SECTION 3.5.4.4.
- DIMENSIONS APPLY TO LANDS ON BOTH SIDES OF THE BOARD.
- THE THICKNESS OF THE OUTER METAL LAYERS, INCLUDING FOIL, COPPER PLATING, AND THE PROTECTIVE SURFACE FINISH, SHALL BE 0.066mm MAXIMUM.
- CHAMFER ROUGHNESS NOT TO EXCEED 3.17 MICROMETERS.
- CHAMFER PROCESS SHALL NOT DAMAGE THE GOLD EDGE LANDS.
- EDGE CARD CHAMFER NOT TO GO THROUGH GOLD LANDS.
- 0.03mm MAXIMUM PLATING OVERHANG ON ALL GOLD LAND EDGES.
- MOLEX RECOMMENDS NO TIE-BARS ON THE LEADING EDGE OF THE GOLD LAND. IF TIE-BARS ARE USED, THEY SHALL BE PLACED TO ONE SIDE OF THE GOLD LAND. APPLIES TO ALL GOLD LANDS.

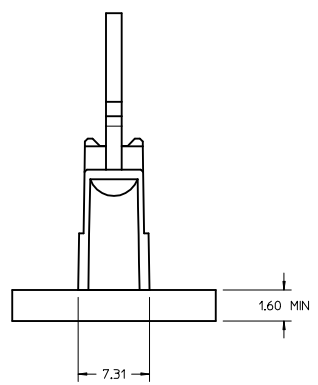
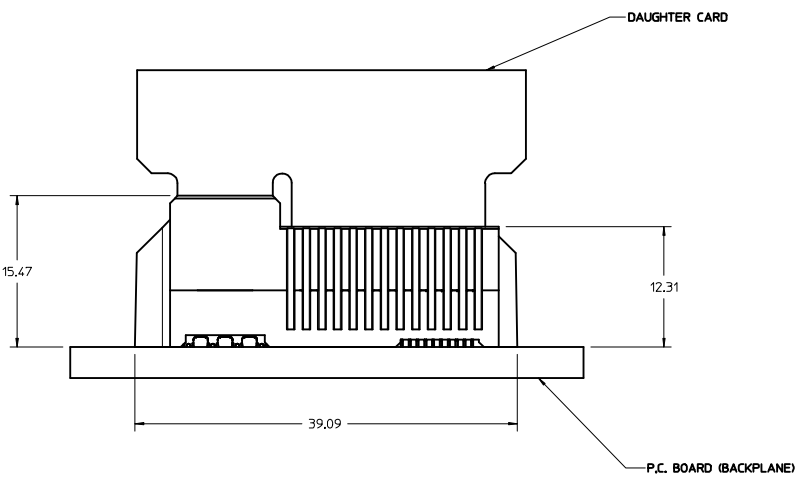
SEE SHEET 1 IEC NO: UICP2017-1945 DRAWN BY: CHYKDMORGAN CHECKED BY: APPR:KLANG DATE: 2017/03/09 DATE: 2017/03/15	QUALITY SYMBOLS ∇=0 ∇=0 ∇=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		4 PLACES ± 0.13 3 PLACES ± 0.25 2 PLACES ± 0.50 1 PLACE ± 1.00 0 PLACE ± 1.50	mm INCH	DRAWN BY: MPOFF CHECKED BY: DMORGAN APPROVED BY: SMILLER DATE: 2014/05/23 DATE: 2014/05/23 DATE: 2014/07/23	TITLE EDGELINE ESP30 12.5GB 0.093"PCB/0.8MM PITCH 54 CKTS	MATERIAL NO. SEE SHEET 1	DOCUMENT NO. SD-170545-1054

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

P.C. BOARD MOUNTING

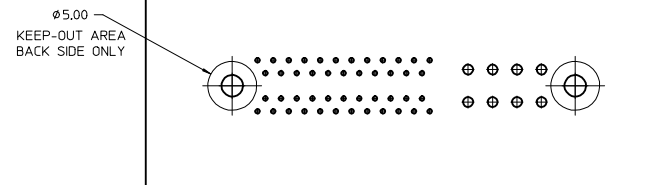
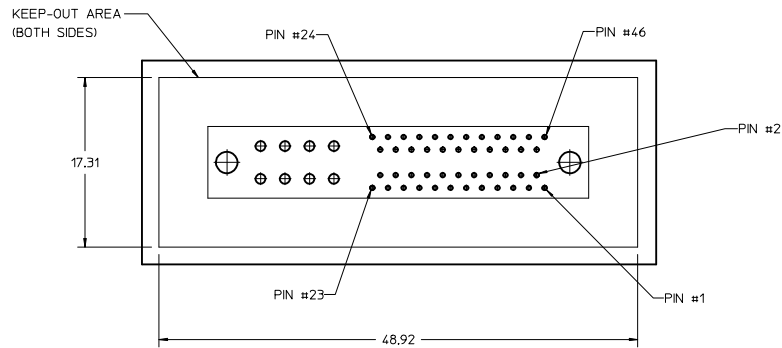
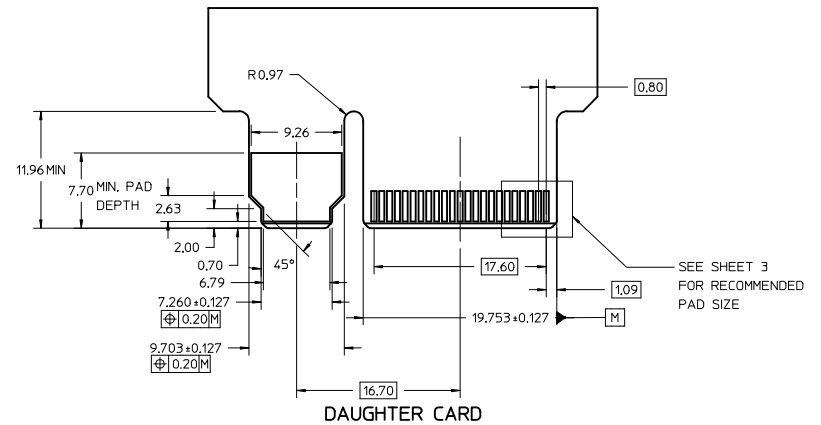
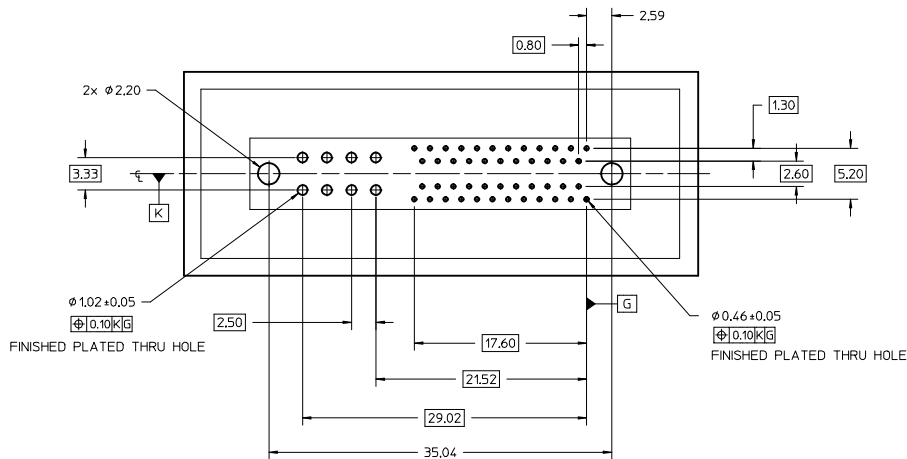


RECOMMENDED THREAD-FORMING SCREW
M1,8x8 (NOT SUPPLIED BY MOLEX)
SEE NOTE 8



- NOTES:
1. MATERIAL:
HOUSING - GLASS FILLED THERMOPLASTIC, 94-V0, BLACK
TERMINALS - COPPER ALLOY
 2. FINISH:
CONTACT AREA: HARD GOLD -0.76µm MIN OVER 3.80µ NICKEL
COMPLIANT AREA: TIN - 0.76/152µm OVER NICKEL
 3. REFER TO PS-76861-100 PRODUCT SPECIFICATION FOR ALL ELECTRICAL, MECHANICAL AND ENVIRONMENTAL SPECIFICATIONS.
 4. REFER TO PK-76861-900 FOR ALL PACKAGING SPECIFICATIONS.
 5. PROCESSING: PRESSFIT TO PC BOARD.
 6. MATING PC BOARD THICKNESS = 1.60±0.16MM OVER CONTACT PADS.
 7. THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPEC PS-45499-002.
 8. REFER TO APPLICATION SPECIFICATION AS-76693-100 FOR MORE DETAILS

DRAWN BY: DROSCA CHECKED BY: JCOMERC I DATE: 12/02/2008 EC NO: UICP 2017-1680 2017/02/17 CHYKOSMORGAN 2017/02/17 APPR:KLANG 2017/02/27	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
	▽=0	4 PLACES ± --- ± ---	MM ONLY	4:1	METRIC	☉	
	▽=0	3 PLACES ± --- ± ---	mm INCH	DRAWN BY DATE	TITLE		
	▽=0	2 PLACES ± 0.13 ± ---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	JCOMERC I 12/02/2008	EDGELINE+LPH 12.5GB 0.062"PCB/0.8MM PITCH 46 CKTS		
		ANGULAR ± 2 °	APPROVED BY DATE	MATERIAL NO.		SHEET NO.	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	JCOMERC I 2009/08/04	76861-1000		1 OF 3	
			DOCUMENT NO.		INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
			SD-76861-100		MOLEX		



MOTHER BOARD HOLE LAYOUT (BACK SIDE)

MOTHER BOARD HOLE LAYOUT (COMPONENT SIDE)

SEE SHEET 1 EC NO: UCP2017-1680 DRAWN BY: CHYKOSMORGAN CHECKED BY: APPR:KLANG DATE: 2017/02/17 DATE: 2017/02/27 DESCRIPTION:	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	$\nabla=0$	4 PLACES \pm mm \pm INCH	MM ONLY	4:1	METRIC	
	$\nabla=0$	3 PLACES \pm mm \pm INCH	DRAWN BY: DROSCA	DATE: 12/02/2008	TITLE: EDGELINE+LPH 12.5GB	
	$\nabla=0$	2 PLACES ± 0.13 \pm INCH	CHECKED BY: JCOMERC I	DATE: 12/02/2008	0.062"PCB/0.8MM PITCH	
	1 PLACE ± 0.25 \pm INCH	APPROVED BY: JCOMERC I	DATE: 2009/08/04	46 CKTS		
	0 PLACE \pm INCH	ANGULAR $\pm 2^\circ$	MATERIAL NO.	DOCUMENT NO.		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE SHEET 1	SD-76861-100			

